BRBSS138Q
Rev.A Apr.-2022

DATA SHEET

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SOT-23 N MOS N-CHANNEL MOSFET in a SOT-23 Plastic Package.

Low $R_{DS(on)}$,rugged and reliable, compact industry standard SOT-23 surface mount pacacp

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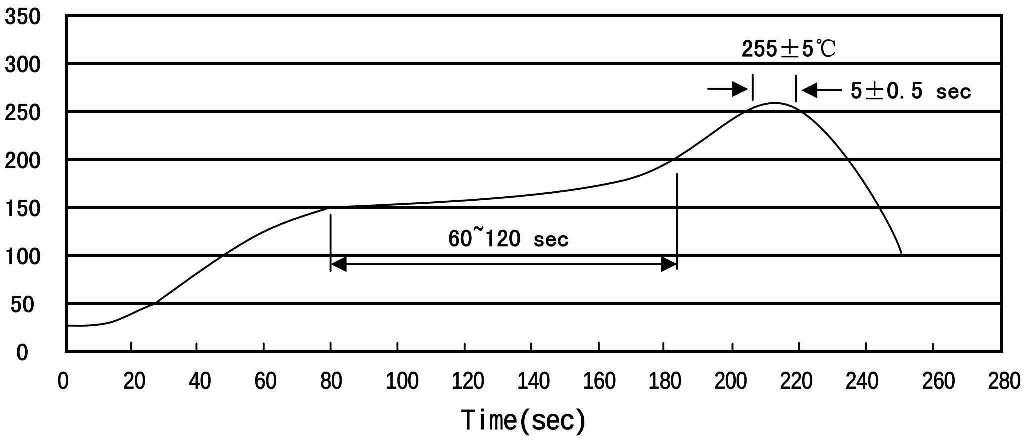
Parameter	k 7 Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	50	V
Gate-Source Voltage	V_{GSS}	±20	V
Drain Current – Continuous	I_D	220	mA
Peak Drain Current	I_{DM}	880	mA
Power Dissipation	P_D	360	mW

Thermal Resistance, Junction-to-

V

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：	Note:
1、预热温度 150～200 ，时间 60～120sec;	1.Preheating:150~200℃, Time:60~120sec.
2、峰值温度 255±5 ，时间持续为 5±0.5sec;	2.Peak Temp.:255±5℃, Duration:5±0.5sec.
3、焊接制程冷却速度为 2～10℃/sec.	3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

温度：260±5℃ 时间：10±1 sec. Temp.:260±5℃ Time:10±1 sec

/ Packaging SPEC.

卷盘包装 / REEL

Package Type !	Units " # $					Dimension " % & (unit ' mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box (	Outer Box)
SOT-23	3,000	10	30,000	6	180,000	7″ ×8	180×120×180	390×385×205

/ Notices